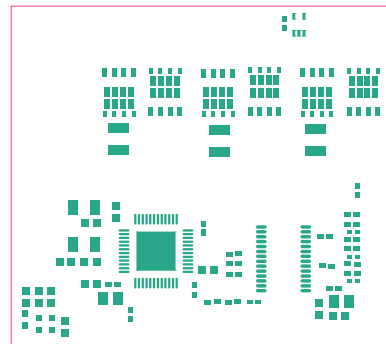
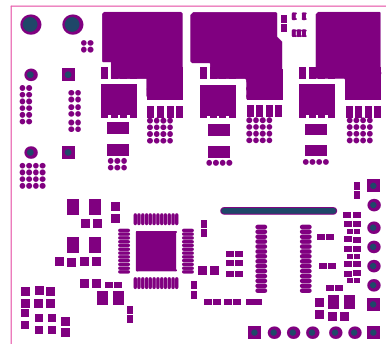


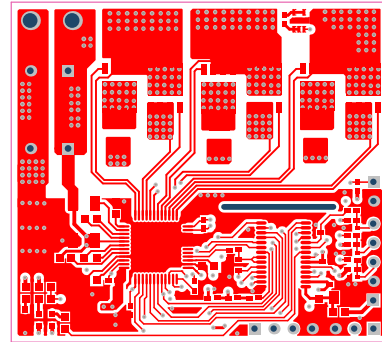
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay	TIDA-00771		
Top Overlay	GENERATED : 3/24/2016	3:33:30 PM	TEXAS INSTRUMENTS



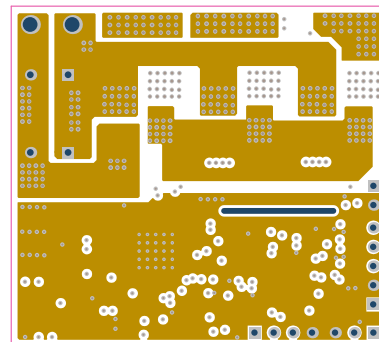
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Paste	TIDA-00771		
Top Paste	GENERATED : 3/24/2016	3:33:30 PM	TEXAS INSTRUMENTS



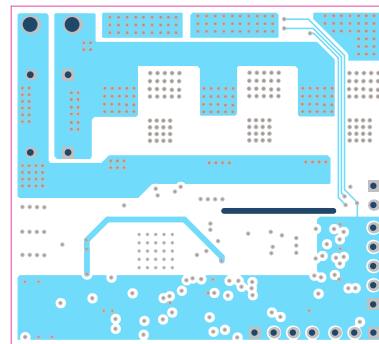
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Solder	TIDA-00771		
Top Solder Mask	GENERATED : 3/24/2016 3:33:31 PM	TEXAS INSTRUMENTS	



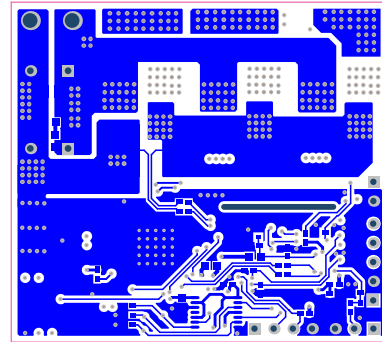
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Top Layer	TIDA-00771		
Top Layer	GENERATED : 3/24/2016 3:33:32 PM	TEXAS INSTRUMENTS	



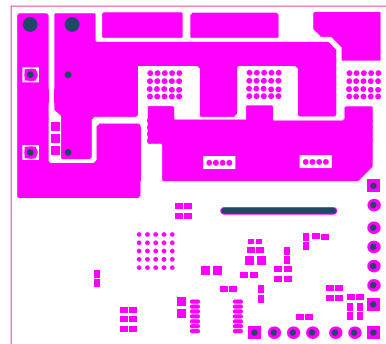
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = GND	TIDA-00771		
GND	GENERATED : 3/24/2016 3:33:32 PM	TEXAS INSTRUMENTS	



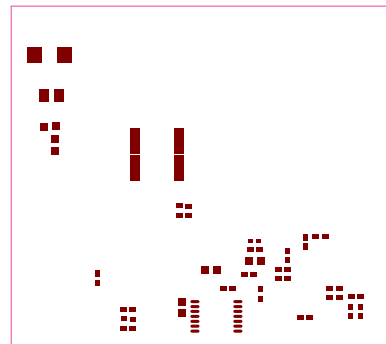
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = PWR	TIDA-00771		
PWR	GENERATED : 3/24/2016 3:33:33 PM	TEXAS INSTRUMENTS	



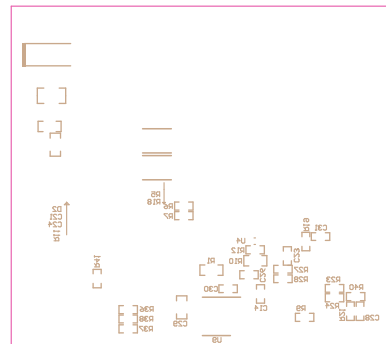
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer	TIDA-00771		
Bottom Layer	GENERATED : 3/24/2016 3:33:33 PM	TEXAS INSTRUMENTS	



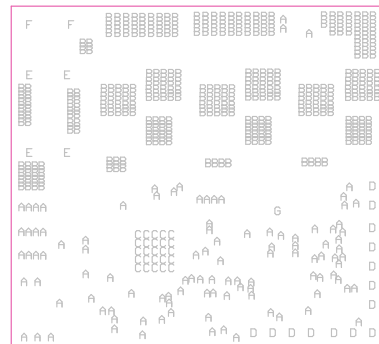
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TIDA-00771		
Bottom Solder Mask	GENERATED : 3/24/2016 3:33:34 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Paste	TIDA-00771		
Bottom Paste	GENERATED : 3/24/2016 3:33:35 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay	TIDA-00771		
Bottom Overlay	GENERATED : 3/24/2016 3:33:35 PM	TEXAS INSTRUMENTS	



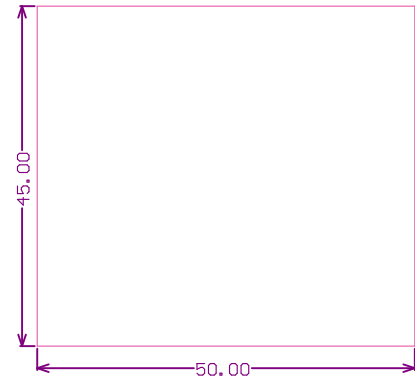
Symbol	Hit Count	Tool Size	Physical Length	Rout Path Length	Plated	Hole Type
C	25	7.874mil (0.2mm)			PTH	Round
A	107	12mil (0.305mm)			PTH	Round
B	312	15mil (0.381mm)			PTH	Round
D	14	33.465mil (0.85mm)			PTH	Round
E	4	35.433mil (0.9mm)			PTH	Round
F	2	78.74mil (2mm)			PTH	Round
G	1	30mil (0.762mm)	600mil (15.24mm)	570mil (14.478mm)	NPTH	Slot
	465 Total					

Slot definitions : Rout Path Length = Calculated from tool start centre position to tool end centre position.
 Physical Length = Rout Path Length + Tool Size = Slot length as defined in the PCB layout

Drill Table

FOR 7.874MIL DRILL +/-7.874MIL
 FOR 12MIL DRILL +/-12MIL
 FOR 15MIL DRILL +/-15MIL
 FOR PTH DRILL +/-3MIL
 FOR NPTH DRILL +/-2MIL

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TIDA-00771		
Drill Drawing	GENERATED : 3/24/2016	3:33:36 PM	TEXAS INSTRUMENTS



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-00771	REV: E2	SUN REV: Not In VersionControl
LAYER NAME =	TIDA-00771		
Board Dimensions	GENERATED : 3/24/2016 3:33:37 PM	TEXAS INSTRUMENTS	

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